## ABSTRACT

A thermosetting resin composition comprising (1) a copolymer resin comprising (a) a monomer unit and (b) a monomer unit respectively represented by the following general formulae (I) and (II):

$$\begin{array}{c|c}
CH_2 & CH_2 &$$

wherein  $R^1$  represents hydrogen, a halogen, or a  $C_1$ - $C_5$  hydrocarbon group;  $R^2$  represents a halogen or a  $C_1$ - $C_5$  hydrocarbon group; x is 0 to 3; and each of m and n is a natural number,

and (2) a cyanate resin having at least two cyanate groups per molecule.

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To provide a printed wiring board material and a printed wiring board for electronic appliance, having a low dielectric constant and a low dielectric dissipation factor as well as improved heat resistance.